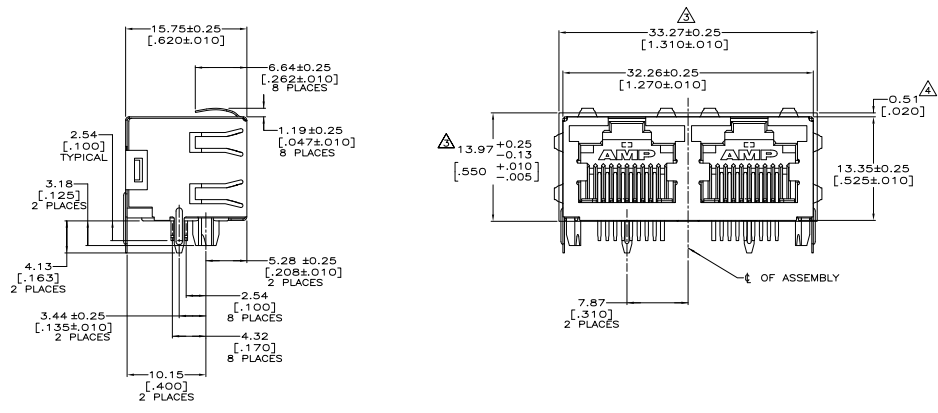
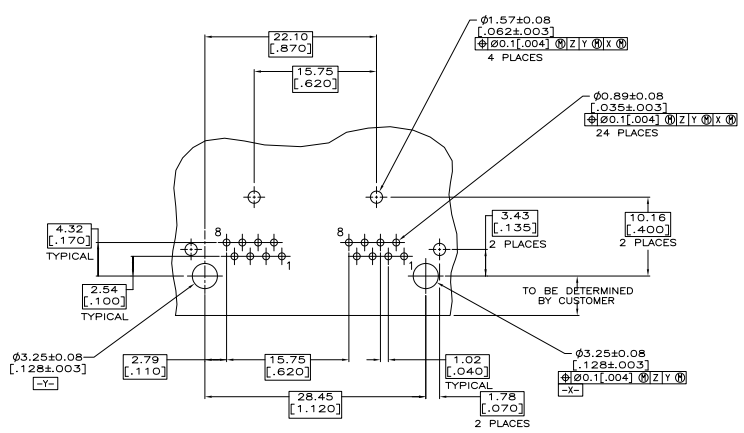


REV	DATE	DESCRIPTION	BY	APP'D
AA	22			
A1		ECR-10-011233		27MAR2010K.S.S.Y.



- ▲ MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
- TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.8[.150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27[.050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27[.050] MINIMUM THICK NICKEL.
- SHIELD - 0.19[.007] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27[.050] MINIMUM SATIN NICKEL WITH 2.03[.080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ▲ SUGGESTED PANEL OPENING DIMENSIONS.
- ▲ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- ▲ TAPE&REEL PACKAGING WITH ANTISTATIC.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	DATE	DESCRIPTION	BY	APP'D
DRAWING LABEL:		AA	22			
DRAWING NUMBER:		108-1163-4				
REVISED BY:		A1				
REVISED DATE:		114-2154				
REVISED DESCRIPTION:		A1 00779 6116522				
REVISED PART NUMBER:		6116522-2				
REVISED PACKAGE:		6116522-1				
REVISED PART NUMBER:		6116522-1				
REVISED PACKAGE:		6116522-1				
REVISED PART NUMBER:		6116522-1				
REVISED PACKAGE:		6116522-1				